## Amendments to the specification:

Kindly replace the title of the invention wherever it appears in the application and supporting documents with the following revised title:

METHOD AND SYSTEM FOR TESTING MULTI-CHIP INTEGRATED
CIRCUIT MODULES

## Amendments to the specification:

Kindly replace the abstract of the disclosure with the following revised abstract:

## ABSTRACT OF THE DISCLOSURE

A system and method for utilizing a multi-probe tester to test an electrical device having a plurality of contact pads. Multi-probe tester test probes and electrical device contact pads are arrayed in a common distribution pitch, and a means for masking test probes masks wherein at least one test probe is masked, thereby preventing the at least one test probe from returning a test result to the testing apparatus. In one embodiment the means for masking test probes is a mask membrane physically preventing prevents at least one test probe from making contact with the electrical device. In another embodiment, the means for masking is at least one software command is provided configured to cause an input from at least one test probe to be disregarded during a test routine. Another embodiment features both mask membrane and software command probe masking.